



NC7SZ126 TinyLogic[®] UHS Buffer with Three-State Output

Features

- Ultra-High Speed: t_{PD} 2.6ns (Typical) into 50pF at 5V V_{CC}
- High Output Drive: ±24mA at 3V V_{CC}
- Broad V_{CC} Operating Range: 1.65V to 5.5V
- Matches Performance of LCX Operated at 3.3V V_{CC}
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak[™] Packages
- Space-Saving SOT23 and SC70 Packages

Description

The NC7SZ126 is single buffer with three-State output from Fairchild's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad $V_{\rm CC}$ operating range. The device is specified to operate over the 1.65V to 5.5V $V_{\rm CC}$ operating range. The inputs and output are high impedance above ground when $V_{\rm CC}$ is 0V. Inputs tolerate voltages up to 6V, independent of $V_{\rm CC}$ operating voltage. The output tolerates voltages above $V_{\rm CC}$ in the 3-State condition.

Ordering Information

| Part Number | Top Mark | © Eco Status | Package | Packing Method |
|-------------|----------|---------------------|--|------------------------------|
| NC7SZ126M5X | 7Z26 | RoHS | 5-Lead SOT23, JEDEC MO-178 1.6mm | 3000 Units on Tape & Reel |
| NC7SZ126P5X | Z26 | RoHS | 5-Lead SC70, EIAJ SC-88a, 1.25mm Wide | 3000 Units on Tape & Reel |
| NC7SZ126L6X | FF | RoHS | 6-Lead MicroPak™, 1.00mm Wide | 5000 Units on Tape & Reel |
| NC7SZ126FHX | FF | Green | 6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch | 5000 Units on Tape & Reel |

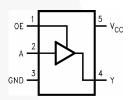
Por Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Connection Diagrams



Figure 1. Logic Symbol

Pin Configurations





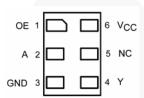


Figure 3. MicroPak (Top Through View)

Pin Definitions

| Pin # SC70 / SOT23 | n # SC70 / SOT23 Pin # MicroPak | | Description |
|--------------------|---------------------------------|-----|----------------|
| 1 | 1 | OE | Input |
| 2 | 2 | A | Input |
| 3 | 3 | GND | Ground |
| 4 | 4 | Υ | Output |
| 5 | 6 | Vcc | Supply Voltage |
| | 5 | NC | No Connect |

Function Table

| In | outs | Output |
|----|------|--------|
| OE | Α | Out Y |
| Н | L | L |
| Н | Н | Н |
| L | X | Z |

H = HIGH Logic Level

L = LOW Logic Level

X = HIGH or LOW Logic Level

Z = HIGH Impedance State

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Para | ameter | Min. | Max. | Unit |
|-------------------------------------|--------------------------------------|------------------------------|------|------|-------|
| V _{CC} | Supply Voltage | | -0.5 | 6.0 | V |
| V _{IN} | DC Input Voltage | | -0.5 | 6.0 | V |
| V _{OUT} | DC Output Voltage | | -0.5 | 6.0 | V |
| I | DC Input Diode Current | V _{IN} < -0.5V | | -50 | mA |
| I _{IK} | DC Input Diode Current | V _{IN} > 6.0V | | +20 | IIIA |
| 1 | DC Output Diada Current | V _{OUT} < -0.5V | | -50 | mA. |
| l _{OK} | DC Output Diode Current | $V_{OUT} > 6V, V_{CC} = GND$ | | +20 | IIIA |
| l _{out} | DC Output Current | | | ±50 | mA |
| I _{CC} or I _{GND} | DC V _{CC} or Ground Current | | | ±50 | mA |
| T _{STG} | Storage Temperature Range | | -65 | +150 | °C |
| T_J | Junction Temperature Under B | ias | | +150 | °C |
| T_L | Junction Lead Temperature (Se | oldering, 10 Seconds) | | +260 | °C |
| | | SOT-23 | | 200 | |
| P_{D} | Power Dissipation at +85°C | SC70-5 | | 150 | mW |
| FD | Fower Dissipation at +65 C | MicroPak-6 | \ \ | 130 | IIIVV |
| | | MicroPak2-6 | | 120 | |
| ESD | Human Body Model, JEDEC:JE | ESD22-A114 | | 4000 | V |
| ESD | Charge Device Model, JEDEC: | JESD22-C101 | | 2000 | |

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter | Conditions | Min. | Max. | Unit | |
|---------------------------------|-------------------------------|------------------------------------|------|------|---------------------------------------|--|
| V _{CC} | Supply Voltage Operating | | 1.65 | 5.50 | V | |
| V CC | Supply Voltage Data Retention | | 1.50 | 5.50 | 7 ° | |
| V _{IN} | Input Voltage | | 0 | 5.5 | V | |
| V | Output Valtage | Active State | 0 | Vcc | V | |
| V _{OUT} | Output Voltage | Three-State | 0 | 5.5 | \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | |
| T _A | Operating Temperature | | -40 | +85 | °C | |
| | | V _{CC} =1.8V, 2.5V ± 0.2V | 0 | 20 | | |
| t _r , t _f | Input Rise and Fall Times | $V_{CC} = 3.3 V \pm 0.3 V$ | 0 | 10 | ns/V | |
| | | $V_{CC}=5.0V \pm 0.5V$ | 0 | 5 | | |
| | | SOT-23 | | 300 | | |
| 0 | Thermal Desistance | SC70-5 | | 425 | 0000 | |
| $\theta_{\sf JA}$ | Thermal Resistance | MicroPak-6 | | 500 | °C/W | |
| | | MicroPak2-6 | | 560 | | |

Note

Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

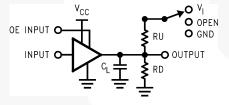
| 0 | D | ter V _{cc} | 0 | T, | T _A =+25°C | | | T _A =-40 to +85°C | |
|------------------|---------------------------------|---------------------|---|---------------------|-----------------------|---------------------|---------------------|------------------------------|-------|
| Symbol | ymbol Parameter V _{cc} | | Conditions Min. | | Тур. | Max. | Min. | Max. | Units |
| 1/ | HIGH Level | 1.65 to 1.95 | | 0.75V _{CC} | | | 0.75V _{CC} | | \/ |
| V_{IH} | Input Voltage | 2.30 to 5.50 | | 0.70V _{CC} | | | 0.70V _{CC} | | V |
| | LOW Level | 1.65 to 1.95 | | | | 0.25V _{CC} | | 0.25V _{CC} | \/ |
| V_{IL} | Input Voltage | 2.30 to 5.50 | | | | 0.30V _{CC} | | 0.30V _{CC} | V |
| | | 1.65 | | 1.55 | 1.65 | | 1.55 | | |
| | | 1.80 | | 1.70 | 1.80 | | 1.70 | | |
| | | 2.30 | V _{IN} =V _{IH} , I _{OH} =-100µA | 2.20 | 2.30 | | 2.20 | | |
| | | 3.00 | | 2.90 | 3.00 | | 2.90 | | |
| | HIGH Level | 4.50 | | 4.40 | 4.50 | | 4.40 | | V |
| V_{OH} | Output Voltage | 1.65 | I _{OH} =-4mA | 1.29 | 1.52 | | 1.29 | | V |
| | | 2.30 | I _{OH} =-8mA | 1.90 | 2.15 | | 1.90 | | |
| | | 3.00 | I _{OH} =-16mA | 2.40 | 2.80 | | 2.40 | | |
| | | 3.00 | I _{OH} =-24mA | 2.30 | 2.68 | | 2.30 | | |
| | | 4.50 | I _{OH} =-32mA | 3.80 | 4.20 | | 3.80 | | |
| | | 1.65 | | | 0.00 | 0.10 | | 0.10 | |
| | 7 | 1.80 | | | 0.00 | 0.10 | | 0.10 | |
| | 7/5 | 2.30 | V _{IN} =V _{IL} ,I _{OL} =100µA | | 0.00 | 0.10 | | 0.10 | |
| | | 3.00 | | | 0.00 | 0.10 | | 0.10 | |
| | LOW Level | 4.50 | | | 0.00 | 0.10 | 1 | 0.10 | |
| V_{OL} | Output Voltage | 1.65 | I _{OL} =4mA | | 0.80 | 0.24 | | 0.24 | V |
| | | 2.30 | I _{OL} =8mA | | 0.10 | 0.30 | | 0.30 | |
| | | 3.00 | I _{OL} =16mA | | 0.15 | 0.40 | | 0.40 | |
| | | 3.00 | I _{OL} =24mA | | 0.22 | 0.55 | | 0.55 | |
| | | 4.50 | I _{OL} =32mA | | 0.22 | 0.55 | | 0.55 | |
| I _{IN} | Input Leakage Current | 0 to 5.5 | V _{IN} =5.5V, GND | | | ±1 | | ±10 | μΑ |
| loz | 3-STATE Output Leakage | 0 to 5.5 | V _{IN} =V _{IH} or V _{IL} V _O =V _{CC} or GND | | | ±1 | | ±10 | μΑ |
| I _{OFF} | Power Off Leakage Current | 0 | V _{IN} or V _{OUT} =5.5V | | | 1 | | 10 | μΑ |
| Icc | Quiescent Supply Current | 1.65 to 5.50 | V _{IN} =5.5V, GND | | | 2 | | 20 | μA |

AC Electrical Characteristics

| Cumbal | Doromotor | V | Conditions | | Γ _A =25° | С | T _A =-40 1 | to +85°C | Units | Ciaura |
|----------------------------------|----------------------------|------------------------------------|--|------|---------------------|------|-----------------------|----------|-------|-----------|
| Symbol Parameter | | V _{CC} | Conditions | Min. | Тур. | Max. | Min. | Max. | Units | Figure |
| | | 1.65 | | 2.0 | 6.4 | 13.2 | 2.0 | 13.8 | | |
| | | 1.80 | C _L =15pF, | 2.0 | 5.3 | 11.0 | 2.0 | 11.5 | | |
| | | 2.50 ± 0.20 | $R_D=1M\Omega$ | 8.0 | 3.4 | 7.5 | 0.8 | 8.0 | | |
| $t_{PLH,}t_{PHL}$ | Propagation Delay | 3.30 ± 0.30 | S ₁ =OPEN | 0.5 | 2.5 | 5.2 | 0.5 | 5.5 | ns | Figure 4 |
| 7 211, 7 112 | ., ., ., | 5.00 ± 0.50 | | 0.5 | 2.1 | 4.5 | 0.5 | 4.8 | | Figure 6 |
| | | 3.30 ± 0.30 | C _L =50pF, | 1.5 | 3.2 | 5.7 | 1.5 | 6.0 | | |
| | | 5.00 ± 0.50 | $R_D=500\Omega$ $S_1=OPEN$ | 0.8 | 2.6 | 5.0 | 0.8 | 5.3 | | |
| | | 1.65 | $\begin{array}{l} C_L \!\!=\!\! 50 p F, \\ R_D \!\!=\!\! 500 \Omega \\ RU \!\!=\!\! 500 \Omega \\ S_1 \!\!=\!\! GND \text{ for } t_{PZH} \\ S_1 \!\!=\!\! V_{IN} \text{ for } t_{PZL} \\ V_{IN} \!\!=\!\! 2^\bullet \!\!\!\!\! V_{CC} \end{array}$ | 2.0 | 8.4 | 15.0 | 2.0 | 15.6 | ns | |
| | | 1.80 | | 2.0 | 6.1 | 11.5 | 2.0 | 12.0 | | |
| $t_{PZL,}t_{PZH}$ | Output Enable Time | 2.50 ± 0.20 | | 1.5 | 3.8 | 8.0 | 1.5 | 8.5 | | |
| | | 3.30 ± 0.30 | | 1.5 | 3.2 | 5.7 | 1.5 | 6.0 | | |
| | | 5.00 ± 0.50 | | 0.8 | 2.3 | 5.0 | 0.8 | 5.3 | | Figure 4 |
| | | 1.65 | C _L =50pF, | 2.0 | 6.5 | 13.2 | 2.0 | 14.5 | 115 | Figure 6 |
| | | 1.80 | $R_D=500\Omega$ | 2.0 | 5.6 | 11.0 | 2.0 | 12 | | |
| $t_{\text{PLZ}}, t_{\text{PHZ}}$ | Output Disable Time | 2.50 ± 0.20 | RU=500Ω S ₁ =GND for t_{PHZ} | 1.0 | 4.0 | 8.0 | 1.0 | 8.5 | | |
| | | 3.30 ± 0.30 | $S_1 = V_{IN}$ for t_{PLZ} | 1.0 | 3.5 | 5.7 | 1.0 | 6.0 | | |
| | 5.00 ± 0.50 | V _{IN} =2•V _{CC} | 0.5 | 2.5 | 4.7 | 0.5 | 5.0 | | | |
| C _{IN} | Input Capacitance | 0.00 | | | 4 | _ | | | pF | |
| C _{OUT} | Output Capacitance | 0.00 | | | 8 | | | | pF | |
| C_{PD} | Power Dissipation | 3.30 | | | 17 | | | | pF | Figure 5 |
| OPD | Capacitance ⁽²⁾ | 5.00 | | | 24 | | | | ρı | i igule 5 |

Note:

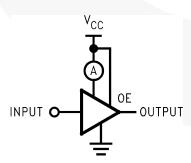
2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output lading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD}=(C_{PD})(V_{CC})(f_{IN})+(I_{CC}static).



Note:

3. C_L includes load and stray capacitance. Input PRR=1.0MHz, t_W =500ns

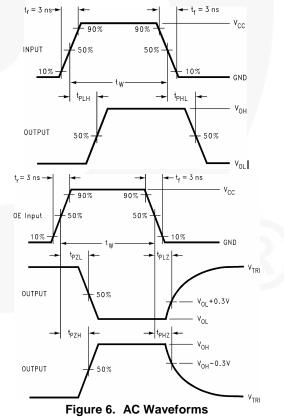
Figure 4. AC Test Circuit



Note:

 Input=AC Waveform; t_r=t_f=1.8ns; PRR=10MHz; Duty Cycle=50%.

Figure 5. I_{CCD} Test Circuit



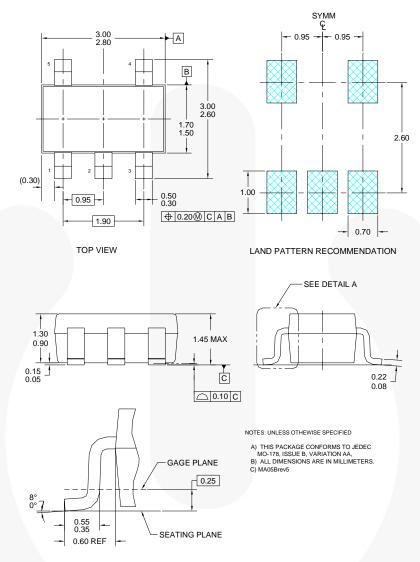


Figure 7. 5-Lead SOT23, JEDEC MO-178 1.6mm

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/SOT23-5L_tr.pdf.

| Package Designator | kage Designator Tape Section | | Cavity Status | Cover Type Status | |
|--------------------|------------------------------|---------------|---------------|-------------------|--|
| | Leader (Start End) | 125 (Typical) | Empty | Sealed | |
| M5X | Carrier | 3000 | Filled | Sealed | |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed | |

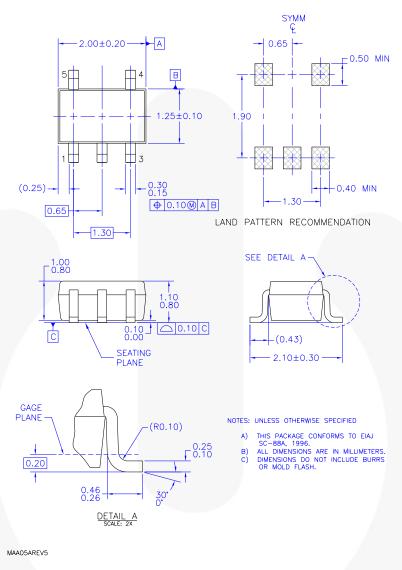


Figure 8. 5-Lead, SC70, EIAJ SC-88a, 1.25mm Wide

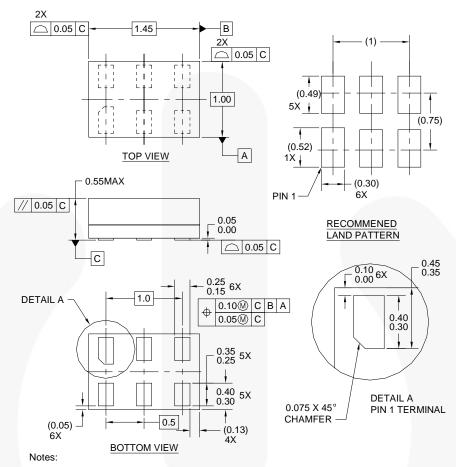
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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/analog/pdf/sc70-5_tr.pdf.

| Package Designator | Package Designator Tape Section | | Cavity Status | Cover Type Status | |
|--------------------|---------------------------------|---------------|---------------|-------------------|--|
| | Leader (Start End) | 125 (Typical) | Empty | Sealed | |
| P5X | Carrier | 3000 | Filled | Sealed | |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed | |



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 9. 6-Lead, MicroPak™, 1.0mm Wide

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| Package Designator | Package Designator Tape Section | | Cavity Status | Cover Type Status | |
|--------------------|---------------------------------|---------------|---------------|-------------------|--|
| | Leader (Start End) | 125 (Typical) | Empty | Sealed | |
| L6X | Carrier | 5000 | Filled | Sealed | |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed | |

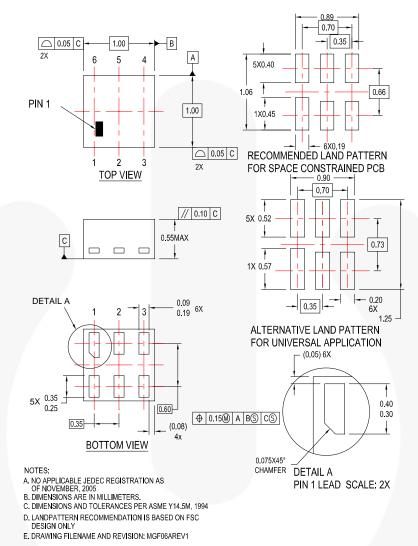


Figure 10.6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2 6L tr.pdf.

| Package Designator Tape Section | | Cavity Number | Cavity Status | Cover Type Status |
|---------------------------------|--------------------|---------------|---------------|-------------------|
| | Leader (Start End) | 125 (Typical) | Empty | Sealed |
| FHX | Carrier | 5000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed |





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|--|-----------------------|---|--|--|--|
| Advance Information | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice. | | | |
| Preliminary | First Production | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. | | | |
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